



Device Material Content

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June, 2026

Package: 400 caBGA
Total Device Weight 0.719 Grams

Package Code:

BBG400

Products:

XO4D

Assembly: ASEK

Size (mm): 17 x 17

Lead pitch (mm): 0.8

MSL: 3

Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.67%	0.0120	1.67%	0.0120	Silicon chip	7440-21-3	100.00%	
Mold Compound	55.60%	0.3999	41.70% 8.06% 2.78% 2.78% 0.28%	0.29993 0.05799 0.02000 0.02000 0.00200	Aluminum oxide Silica Epoxy resin Phenol Resin Carbon Black	1344-28-1 60676-86-0 - - 1333-86-4	75.00% 14.50% 5.00% 5.00% 0.50%	Mold Compound: Kyocera KE-G1250AHT
D/A Epoxy	0.60%	0.0043	0.515% 0.035% 0.029% 0.006% 0.011% 0.001%	0.00370 0.00025 0.00021 0.00004 0.00008 0.00001	Silver (Ag) 2,2-dimethyl-1,3 Propanediyl Bismethacrylate A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol Perfluoropolyoxyalkane ether 2-[[2,2 bis[[[(1-oxoallyloxy)methyl]butoxy)methyl]-2-ethyl-1,3-propanediyl diacrylate bis(4-tert-butylcyclohexyl) peroxydicarbonate	7440-22-4 1985-51-9 - 925918-64-5 94108-97-1 15520-11-3	86.09% 5.92% 4.92% 1.00% 1.88% 0.19%	Die attach epoxy: Henkel (Ablebond) 2100A
Wire	0.39%	0.0028	0.38% 0.01% 0.00%	0.00272 0.00007 0.000008	Copper (Cu) Palladium (Pd) Gold (Au)	7440-50-8 7440-05-3 7440-57-5	97.20% 2.50% 0.30%	AuPCC+, 0.02mm dia
Solder Balls	15.54%	0.1118	15.00% 0.47% 0.08%	0.1079 0.00335 0.00056	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	96.50% 3.00% 0.50%	SAC305
Substrate	10.22%	0.0735	2.12% 1.15% 1.15% 1.15% 0.83% 3.80%	0.0152 0.0083 0.0083 0.0083 0.0060 0.0274	Continuous Filament Fiber Glass Bismaleimide Triazine Cyanic acid (1-methylethylidene)di-4,1-phenylene ester homopolymer Other Resin Aluminum Hydroxide Copper	65997-17-3 105391-33-1 25722-66-1 9003-36-5 21645-51-2 7440-50-8	20.717% 11.300% 11.300% 11.300% 8.161% 37.223%	BT Resin CCL-HL832NX-A
Foil	5.24%	0.0377	4.06% 1.00% 0.19%	0.0292 0.0072 0.0014	Copper Nickel plating Gold plating	7440-50-8 7440-02-0 7440-57-5	77.39% 19.02% 3.59%	
Solder mask	10.75%	0.0773	6.04% 1.72% 2.36% 0.32% 0.30%	0.04344 0.01237 0.01701 0.00232 0.00216	Quartz 3-methoxy-3-methylbutylacetate Barium Sulfate Talc (containing no asbestiform fibers) Trade secret ingredients	14808-60-7 103429-90-9 7727-43-7 14807-96-6 -	56.20% 16.00% 22.00% 3.00% 2.80%	Solder mask PSR4000 AUS 320
	100.00%	0.762	100.00%	0.719			800.00%	

Note:

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Rev. A